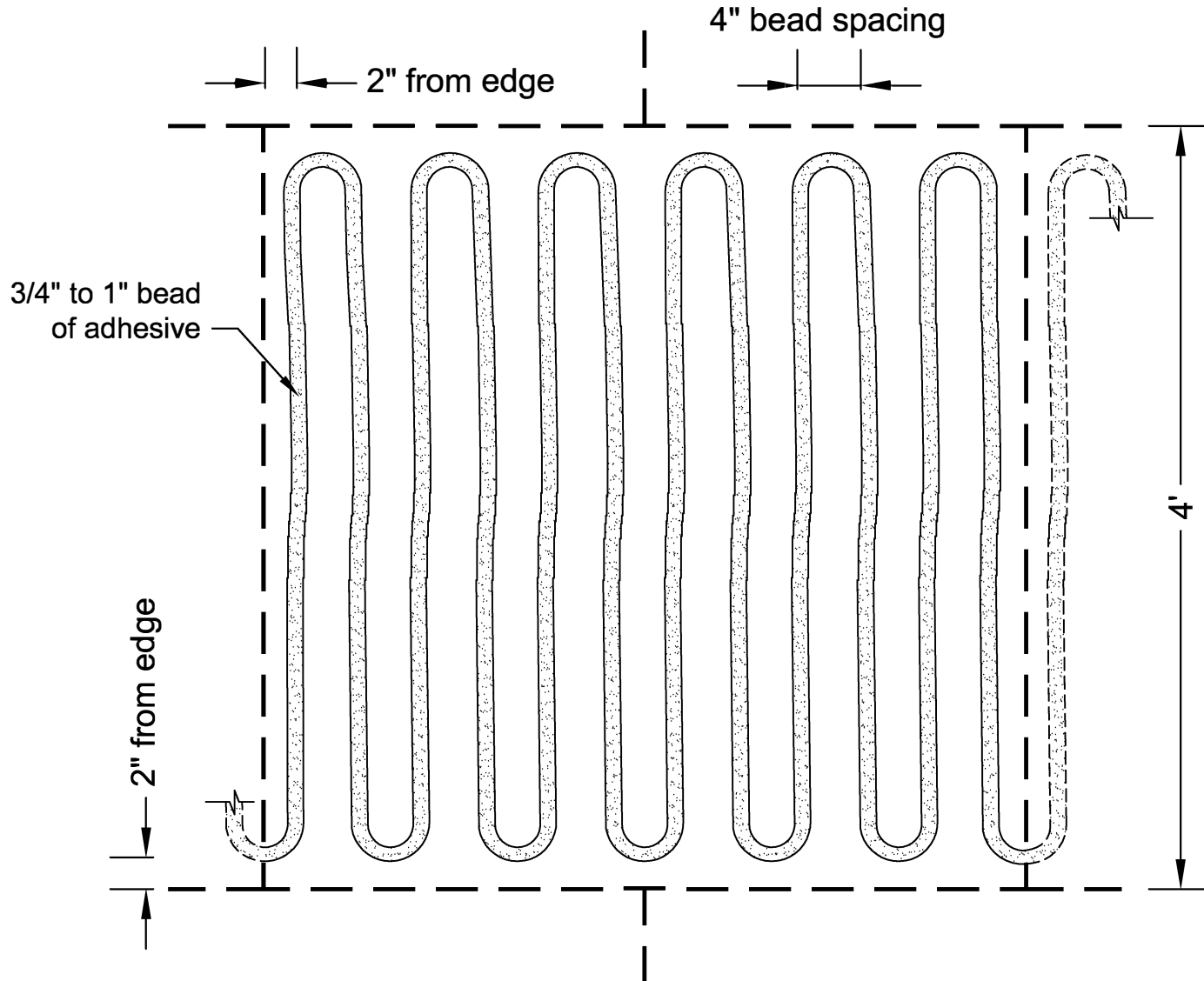


PARA-STIK & PARAFAST BEAD SPACING

4' X 4' INSULATION PANEL
4" BEAD SPACING



- NOTES: 1. THE ABOVE BEAD SPACING FREQUENCY IS INTENDED AS A GUIDELINE FOR INSULATION ADHESION BELOW SIPLAST MEMBRANE SYSTEMS AND IS SUBJECT TO SIPLAST AND INDUSTRY STANDARD REQUIREMENTS.
2. BEADS OF ADHESIVE APPLIED AT 4-INCHES O.C. WILL SPREAD TO OFFER NEAR-FULL COVERAGE. INSULATION PANELS MAY RISE FOLLOWING APPLICATION DUE TO POST GROWTH OF THE ADHESIVE AND MAY REQUIRE REPEATED WALK-IN OR TEMPORARY BALLAST UNTIL THE ADHESIVE CURES.

N.T.S.